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Indium Corporation Engineer Examines Key Factors Impacting Improvements in Metal TIMs at TestConX 2026

CLINTON, N.Y., February 17, 2026 — Indium Corporation Technical Support Engineer Carson Burt will deliver a technical presentation at TestConX 2026, taking place March 1-4 in Mesa, Arizona.


Carson Burt

The session, *The Impact of Time, Pressure, Thickness, and Patterning on Compressible Metal Thermal Interface Materials*, will examine how key design and process variables drive the thermal performance benefits of compressible metal thermal interface materials (TIMs). The findings reflect the collaborative research conducted by Burt and Indium Corporation colleagues Bob Jarrett, Miloš Lazić, Ryan Mayberry, Ricky McDonough, and Emin Skiljan.

"Our team explored how time, pressure, thickness, and patterning influence effective thermal resistance and bondline thickness (BLT), and how optimizing these parameters can improve heat transfer efficiency and reliability," Burt said. "The talk will illustrate how the team's use of the ASTM D5470 test method revealed relationships between each variable and provided actionable insights for maximizing thermal performance in demanding TIMs applications."

In his role as a Technical Support Engineer, Burt provides specialized assistance to optimize the selection and use of Indium Corporation materials and delivers product and process training. He earned a bachelor's degree in chemistry from Clarkson University and is a Certified SMT Process Engineer (CSMTPE).

TestConX 2026 attendees can join the presentation on Wednesday, March 4, 10:30 a.m. MST. For more information on Indium Corporation's Compressible TIMs products, visit the Indium Corporation experts at show booth #46.

About Indium Corporation

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